

SPUTTER TARGET ASSEMBLIES HAVING A CONTROLLED SOLDER THICKNESS

The present invention relates to a method and apparatus of forming a sputter target assembly having a controlled solder thickness. In particular, the method includes the introduction of a bonding foil (20), between the backing plate (16) and the sputter target (10), wherein the bonding foil (20) is an ignitable heterogeneous stratified structure for the propagation of an exothermic reaction.

FIGURE 1